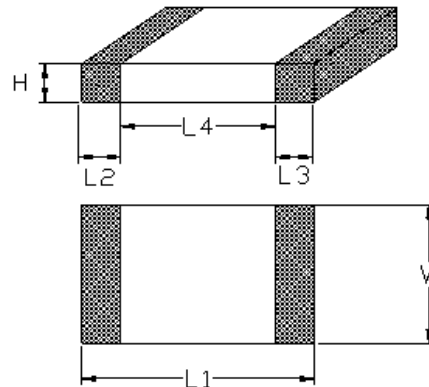


Multilayer Ceramic Chip Capacitor

Part Number : 0805Y0500104KXTM01

Description : 0805 50V 100nF $\pm 10\%$ X7R (2R1)

Syfer Technology Ltd offers Multilayer Ceramic Chip Capacitors of the highest quality and reliability for a range of demanding applications. Manufactured using our "Wet Process", the range encompasses 10V to 12kV capability, with a variety of termination options including FlexiCap™, the worlds first commercially available flexible termination.



Mechanical Specification

Syfer Size Code	0805
Length (L1) mm	2.0 $\pm$ 0.3
Width (W) mm	1.25 $\pm$ 0.2
Thickness (H) mm	1.3 Max.
Termination Bands (L2,L3) mm	0.13 - 0.75
Minimum Band Gap (L4) mm	0.2
Termination Material	100% Matte Sn over Ni, FlexiCap™ base
Solderability	IEC 60068-2-58
RoHS Compliant to 2011/65/EC	Yes
REACH Compliant	Yes
Packaging	Taped and Reeled, 7 inch Reel

General Electric Specifications

Rated Voltage	50V	
Nominal Capacitance Value	100nF	
Capacitance Tolerance	±10%	
Tangent of Loss Angle (Tan δ)	≤0.025	
Capacitance and Tan δ Test Conditions	1Vrms @ 1kHz	
Voltage Proof (Voltage applied for 5 secs max. @ 50mA max. charge current)	2.5 x Rated Voltage	
Min Insulation Resistance (IR)	10 GΩ	
Dielectric Classification	X7R (2R1)	
Rated Temperature Range	-55°C - +125°C	
Maximum Capacitance Change over Temperature Range	No DC Voltage	±15%
	Rated DC Voltage	-
Climatic Category (IEC)	55/125/56	
Ageing Characteristic	Less than 2% per time decade	

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Date: 25 April 2016